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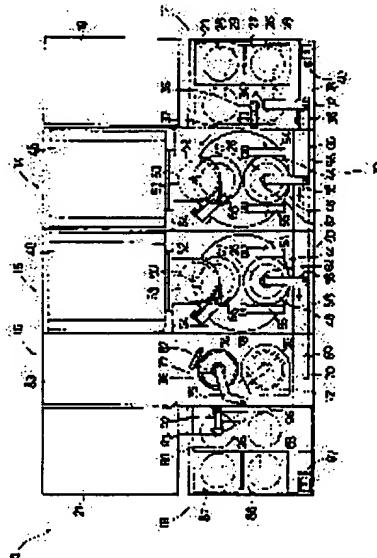
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(54) AUTOMATIC WAFER GRINDING DEVICE

(57)Abstract:

PURPOSE: To deal with diversification in the wafer required, by unitizing a special purpose machine to perform each process in an automatic wafer grinding device for independence, and assembling necessary units of grinding units according to requisite grinding specifications.

CONSTITUTION: Wafers 26 are successively taken out in order of wafer cassettes 22 and 23 by a wafer loading unit 12, fed to grinding units 14 and 15 by a transfer unit 20, and each position of spindles 50 is set up so as to cause each wheel edge of respective grinding wheels 53 to be situated at the center of the wafer 26, thus each wafer is ground into the specified thickness by grinding at two times. Next, the wafer is mounted on a spinner table 72 of a washing unit 16 and washed clean and, after its surface roughness is detected by a roughness measuring instrument 82 by rotation of a swing arm 76, then these wafers are successively housed in empty cassettes 86 and 87 by a wafer unload unit 18. Here, since each unit is independently constituted, necessary units of grinding units are assembled according to requisite specifications, whereby they can deal with multifarious demands.



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